

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: MOROZOV=2C

In re Application of:	)	Art Unit:
	)	
MOROZOV et al.	)	Examiner:
	)	
Appln. No.: NOT YET ASSIGNED	)	Washington, D.C.
	)	
Filed: ON EVEN DATE HERewith	)	November 8, 2001
	)	
For: ELECTROSPRAYING SOLUTIONS	)	
OF SUBSTANCES FOR MASS	)	
FABRICATION OF CHIPS AND	)	
LIBRARIES	)	

PRELIMINARY AMENDMENT

Honorable Commissioner of Patents  
Washington, D.C. 20231

Sir:

Contemporaneous with the filing of this case and  
prior to calculation of the filing fee, kindly amend as  
follows:

IN THE SPECIFICATION

Please replace the paragraph beginning at page 1,  
line 4, with the following rewritten paragraph:

--This is a divisional of application no.  
09/446,188, filed May 8, 2000, which is a 371 national stage  
application PCT/US98/12768, filed June 19, 1998, which claims  
the benefit of priority from U.S. provisional application nos.  
60/050,274, filed June 20, 1997, and 60/055,287, filed August  
13, 1997, the entire contents of application ns. 09/446,188,

PCT/US98/12768, 60/050,274, and 60/055,287 are hereby incorporated by reference.--

Please replace the paragraph beginning at page 7, line 11, with the following rewritten paragraph:

--Figure 1A is a schematic of an electrospray process illustrating the different state of the sprayed substance at different distances from the electrospray capillary tip. Figure 1B is an enlarged partial of Fig. 1A view showing that microdroplets of solution predominate in the wet zone, and dry clusters and ions predominate in the dry zone.--

Please replace the paragraph beginning at page 8, line 9, with the following rewritten paragraph:

--Figure 9A schematically shows the mass fabrication of multicomponent matrices by using a means for shifting the position of the mask relative to the substrate after each of a series of substances are electrodeposited onto a substrate through the holes in the mask. Figure 9B shows an enlarged partial view of Fig. 9A.--

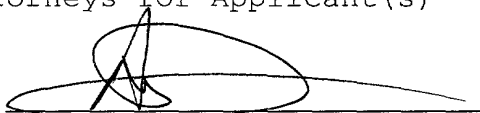
**REMARKS**

The specification is being amended to update the Cross-Reference to Related Applications section and to provide consistency with the formal drawings submitted.

Favorable consideration is respectfully solicited.

Respectfully submitted,

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By 

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

The paragraph beginning at page 1, line 4, has been replaced with the following rewritten paragraph:

~~The present application claims priority from U.S. provisional applications serial no. 60/050,274, filed June 20, 1997, and serial no. 60/055,287, filed August 13, 1997, the entire contents of which are hereby incorporated by reference.~~

This is a divisional of application no. 09/446,188, filed May 8, 2000, which is a 371 national stage application PCT/US98/12768, filed June 19, 1998, which claims the benefit of priority from U.S. provisional application nos. 60/050,274, filed June 20, 1997, and 60/055,287, filed August 13, 1997, the entire contents of application ns. 09/446,188, PCT/US98/12768, 60/050,274, and 60/055,287 are hereby incorporated by reference.

The paragraph beginning at page 7, line 11, has been replaced with the following rewritten paragraph:

Figure 1A is a schematic of an electrospray process illustrating the different state of the sprayed substance at different distances from the electrospray capillary tip.

Figure 1B is an enlarged partial view of Fig. 1A showing that

Microdroplets of solution predominate in the wet zone, and dry clusters and ions predominate in the dry zone.

The paragraph beginning at page 8, line 9, has been replaced with the following rewritten paragraph:

Figure 9A schematically shows the mass fabrication of multicomponent matrices by using a means for shifting the position of the mask relative to the substrate after each of a series of substances are electrodeposited onto a substrate through the holes in the mask. Figure 9B shows an enlarged partial view of Fig. 9A.